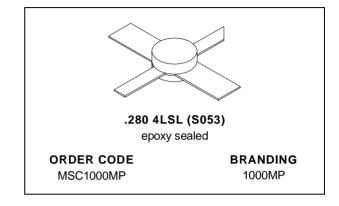


# MSC1000MP

# RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- RUGGEDIZED VSWR ∞:1
- INPUT MATCHING
- LOW THERMAL RESISTANCE
- CLASS A OPERATION
- P<sub>OUT</sub> = 0.6 W MIN. WITH 10.8 dB GAIN

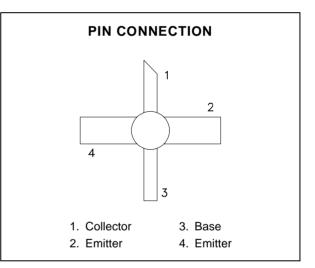


#### DESCRIPTION

The MSC1000MP is a Class A, common emitter transistor with an emitter ballasted Matrix geometry specifically designed for DME/IFF driver applications.

This device is capable of withstanding a  $\infty$ :1 load VSWR at any phase angle under full rated conditions. Low RF thermal resistance and semi-automatic wire bonding techniques ensure high reliability and product consistency.

The MSC1000MP is housed in the IMPAC<sup>TM</sup> package with internal input matching.



#### **ABSOLUTE MAXIMUM RATINGS** ( $T_{case} = 25^{\circ}C$ )

Symbol	Parameter	Value	Unit
P <sub>DISS</sub>	Power Dissipation* (See Safe Area)	—	W
Ι <sub>C</sub>	Device Current*	300	mA
V <sub>CE</sub>	Collector-Emitter Bias Voltage*	20	V
TJ	Junction Temperature (Pulsed RF Operation)	200	°C
T <sub>STG</sub>	Storage Temperature	– 65 to +150	°C

#### THERMAL DATA

R <sub>TH(j-c)</sub>	Junction-Case Thermal Resistance*	35	°C/W				
*Applies only to rated RE amplifier operation							

\*Applies only to rated RF amplifier operation

## MSC1000MP

#### **ELECTRICAL SPECIFICATIONS** $(T_{case} = 25^{\circ}C)$

STATIC

Symbol	Test Conditions	Value			11:0:4		
		Min.	Тур.	Max.	Unit		
BV <sub>CBO</sub>	$I_C = 1mA$	$I_E = 0mA$		50	_		V
BV <sub>EBO</sub>	$I_E = 1mA$	$I_C = 0 m A$		3.5			V
BVCEO	IC = 5mA	$I_B = 0mA$		20			V
ICES	$V_{CE} = 28V$					1.0	mA
hFE	$V_{CE} = 5V$	$I_C = 100 \text{mA}$		15		120	_

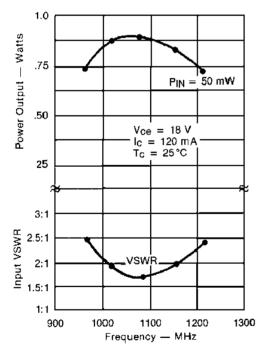
#### DYNAMIC

Symbol	bol Test Conditions		Value			Unit
Symbol			Min.	Тур.	Max.	Unit
Роит	$f = 1025 - 1150 \text{ MHz}$ $P_{IN} = 50 \text{ mW}$	$V_{CE} = 18 V$	0.6	0.85	_	W
GP	$f = 1025 - 1150 \text{ MHz}$ $P_{IN} = 50 \text{ mW}$	$V_{CE}=18\ V$	10.8	12.3	_	dB

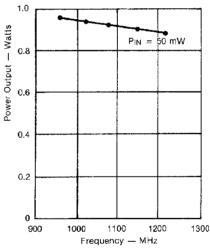
Note: Pulse Width =  $10\mu$ Sec I<sub>C</sub> = 120mADuty Cycle = 1%

## TYPICAL PERFORMANCE

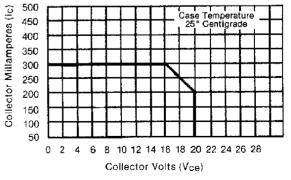
#### **BROADBAND POWER AMPLIFIER**



#### NARROWBAND POWER OUTPUT vs FREQUENCY

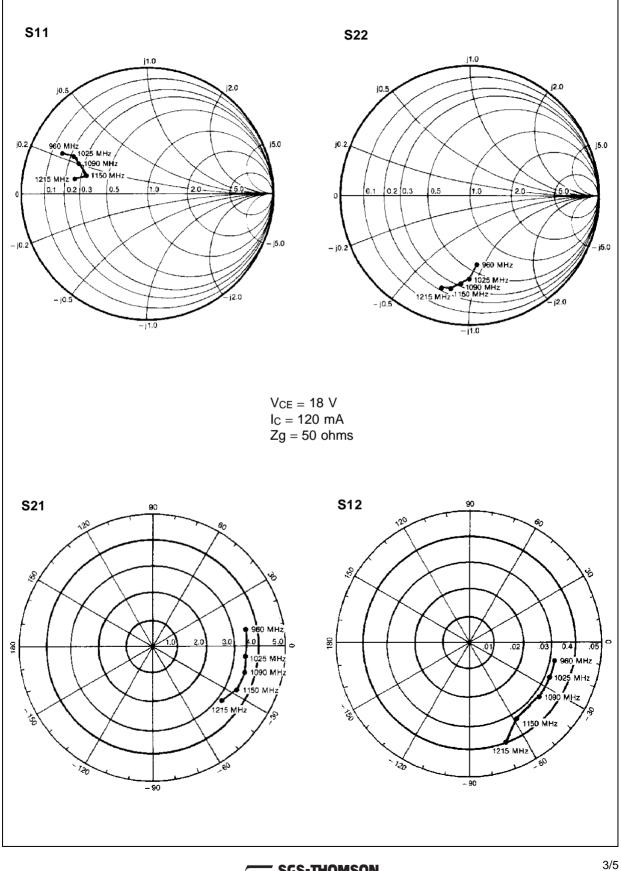


#### MAXIMUM OPERATING AREA for FORWARD BIAS OPERATION



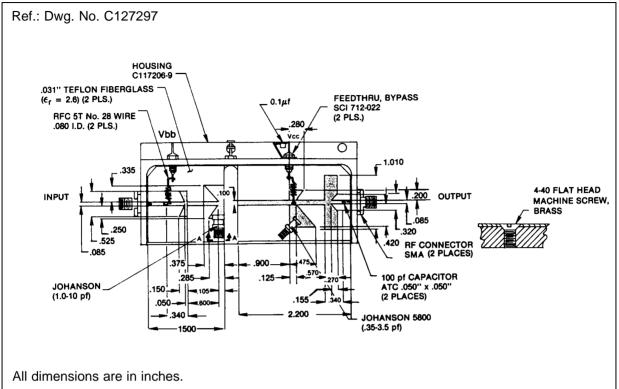


#### TYPICAL S-PARAMETERS

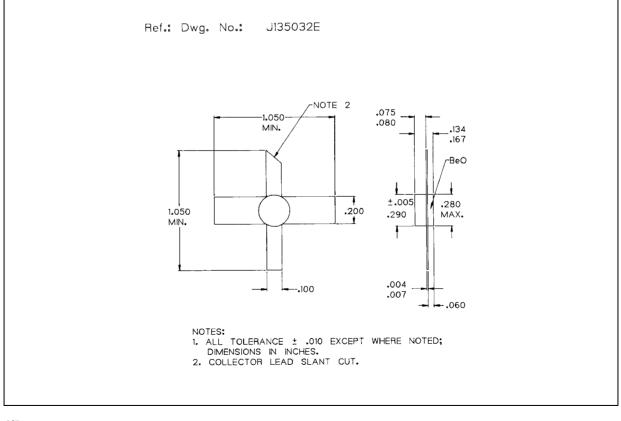


SGS-THOMSON MICROELECTRONICS

#### **TEST CIRCUIT**



# PACKAGE MECHANICAL DATA



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